



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50R1K4CE	Issued	25. June 2021
MA#	MA005558556		
Package	PG-TO252-3-344	Weight*	321.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.378	0.43	0.43	4282	4282
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		165	
	non noble metal	iron	7439-89-6	0.177	0.06		550	
	non noble metal	copper	7440-50-8	176.899	54.95	55.03	549444	550159
wire	non noble metal	aluminium	7429-90-5	0.526	0.16	0.16	1633	1633
encapsulation	organic material	carbon black	1333-86-4	0.687	0.21		2133	
	plastics	epoxy resin	-	18.545	5.76		57600	
	inorganic material	silicon dioxide	60676-86-0	118.137	36.69	42.66	366930	426663
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11907	11907
solder	non noble metal	tin	7440-31-5	0.034	0.01		107	
	noble metal	silver	7440-22-4	0.043	0.01		134	
	non noble metal	lead	7439-92-1	1.647	0.51	0.53	5115	5356
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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